

Sonosystems®

ULTRASONIC WELDING FLEX PRINTED CIRCUITS (FPC)

- Telectrical contacting without removing of the carrier layer, e.g. polyimide, with ultrasonic welding
- Established interconnection technology with known long-term stability
- ¬ Various fields of application e.g. EV: current sensing with FPC
- ¬ Latest machine generation with servo drive, 20/35 kHz technology
- ¬ Various FPC configurations possible:

 □ base material: PI, PET (PEN possible)

 - conducter layer: Cu, Al
 - layer structure: glued or glueless





Layer Structure







